INTEGRATED CIRCUITS

DATA SHEET

74F273AOctal D flip-flop

Product specification

1996 Mar 12

IC15 Data Handbook





Octal D flip-flop

74F273A

FEATURES

- High impedance inputs for reduced loading (20µA in Low and High states)
- Ideal buffer for MOS microprocessor or memory
- Eight edge-triggered D-type flip-flops
- Buffered common clock
- Buffered asynchronous Master Reset
- See 74F377A for clock enable version
- See 74F373 for transparent latch version
- See 74F374 for 3-State version

DESCRIPTION

The 74F273 has eight edge—triggered D–type flip—flops with individual D inputs and Q outputs. The common buffered Clock (CP) and Master Reset ($\overline{\text{MR}}$) inputs load and reset (clear) all flip—flops simultaneously.

The register is fully edge—triggered. The state of each D input, one setup time before the Low—to—High clock transition, is transferred to the corresponding flip—flop's Q output.

All outputs will be forced Low independently of Clock or Data inputs by a Low voltage level on the $\overline{\text{MR}}$ input. The device is useful for applications where the true output only is required and the CP and $\overline{\text{MR}}$ are common to all elements.

TYPE	TYPICAL f _{MAX}	TYPICAL SUPPLY CURRENT (TOTAL)
74F273A	170MHz	25mA

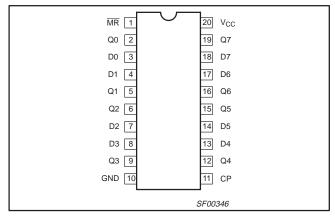
ORDERING INFORMATION

PACKAGES	COMMERCIAL RANGE $V_{CC} = 5V\pm10\%;$ $T_{amb} = 0^{\circ}C \text{ to } +70^{\circ}C$	PKG. DWG. #
20-pin plastic DIP	74F273AN	SOT146-1
20-pin plastic SOL	74F273AD	SOT163-1

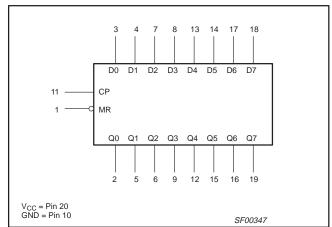
INPUT AND OUTPUT LOADING AND FAN-OUT TABLE

PINS	DESCRIPTION	74F(U.L.) HIGH/LOW	LOAD VALUE HIGH/LOW
D0 – D7	Data inputs	1.0/0.033	20μΑ/20μΑ
MR	Master Reset input (active-Low)	1.0/0.033	20μΑ/20μΑ
СР	Clock pulse input (active rising edge)	1.0/0.033	20μΑ/20μΑ
Q0 – Q7	Data outputs	50/33	1.0mA/20mA

PIN CONFIGURATION



LOGIC SYMBOL

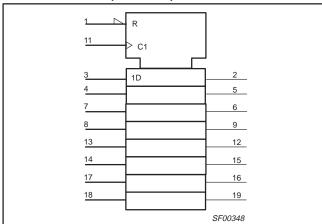


Product specification Philips Semiconductors

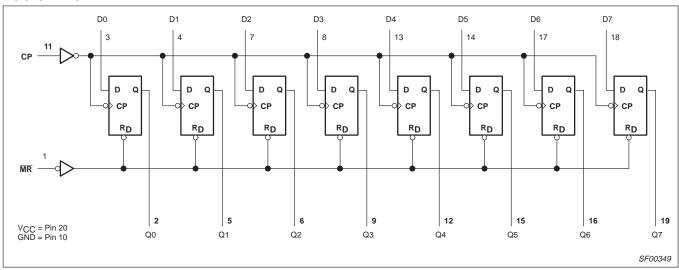
Octal D flip-flop

74F273A

LOGIC SYMBOL (IEEE/IEC)



LOGIC DIAGRAM



FUNCTION TABLE

	INPUTS		OUTPUTS	OPERATING
MR	СР	Dn	Q0 – Q7	MODE
L	Х	Х	L	Reset (clear)
Н	↑	h	Н	Load "1"
Н	↑	I	L	Load "0"

H = High voltage level

High voltage level one set-up time prior to the Low-to-High clock transition

Low voltage level
Low voltage level one set-up time prior to the Low-to-High clock transition

= Don't care

Low-to-High clock transition

Octal D flip-flop

74F273A

ABSOLUTE MAXIMUM RATINGS

(Operation beyond the limit set forth in this table may impair the useful life of the device. Unless otherwise noted these limits are over the operating free air temperature range.)

SYMBOL	PARAMETER	RATING	UNIT
V _{CC}	Supply voltage	-0.5 to +7.0	V
V _{IN}	Input voltage	-0.5 to +7.0	V
I _{IN}	Input current	-30 to +5	mA
V _{OUT}	Voltage applied to output in High output state	–0.5 to V _{CC}	V
I _{OUT}	Current applied to output in Low output state	40	mA
T _{amb}	Operating free air temperature range	0 to +70	°C
T _{stg}	Storage temperature range	-65 to +150	°C

RECOMMENDED OPERATING CONDITIONS

SYMBOL	PARAMETER		UNIT		
		MIN	TYP	MAX	
V _{CC}	Supply voltage	4.5	5.0	5.5	V
V _{IH}	High-level input voltage	2.0			V
V _{IL}	Low-level input voltage			0.8	V
I _{lk}	Input clamp current			-18	mA
I _{OH}	High-level output current			-1	mA
I _{OL}	Low-level output current			20	mA
T _{amb}	Operating free air temperature range	0		+70	°C

1996 Mar 12 4

Octal D flip-flop 74F273A

DC ELECTRICAL CHARACTERISTICS

(Over recommended operating free-air temperature range unless otherwise noted.)

SYMBOL	PARAMETER		TEST			LIMITS		UNIT
			CONDITIONS ¹	MIN	TYP ²	MAX		
		MR & CP	$V_{CC} = MIN, V_{IL} = 0.0V^3,$	±10%V _{CC}	2.5			V
V_{OH}	High-level output voltage	inputs	$V_{IH} = 4.5V^3$, $I_{OH} = MAX$	±5%V _{CC}	2.7	3.4		V
		other	$V_{CC} = MIN, V_{IL} = MAX,$	±10%V _{CC}	2.5			V
		inputs	$V_{IH} = MIN, I_{OH} = MAX$	±5%V _{CC}	2.7	3.4		V
V_{OL}	Low-level output voltage	Low-level output voltage		±10%V _{CC}		0.30	0.50	V
			$V_{IH} = MIN, I_{OH} = MAX$	±5%V _{CC}		0.30	0.50	V
V_{IK}	Input clamp voltage		$V_{CC} = MIN, I_I = I_{IK}$		-0.73	-1.2	V	
l _l	Input current at maximum input vo	ltage	$V_{CC} = 0.0V, V_I = 7.0V$			100	μΑ	
I _{IH}	High-level input current		$V_{CC} = MAX, V_I = 2.7V$				20	μΑ
I _{IL}	Low-level input current		$V_{CC} = MAX, V_I = 0.5V$				-20	μΑ
Ios	Short-circuit output current ⁴		V _{CC} = MAX		-60		-150	mA
Icc	Supply current (total)	I _{CCH}	V _{CC} = MAX			24	38	mA
		I _{CCL}				27	43	mA

NOTES:

- 1. For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions for the applicable type.
- 2. All typical values are at $V_{CC} = 5V$, $T_{amb} = 25^{\circ}C$. 3. To reduce the effect of external noise during test.
- 4. Not more than one output should be shorted at a time. For testing I_{OS}, the use of high-speed test apparatus and/or sample-and-hold techniques are preferable in order to minimize internal heating and more accurately reflect operational values. Otherwise, prolonged shorting of a high output may raise the chip temperature well above normal and thereby cause invalid readings in other parameter tests. In any sequence of parameter tests, IOS tests should be performed last.

AC CHARACTERISTICS FOR 'F273A

					UNIT			
SYMBOL	PARAMETER	WAVEFORM	$T_{amb} = +25^{\circ}C$ $V_{CC} = +5.0V$ $C_{L} = 50pF$ $R_{L} = 500\Omega$			T _{amb} = 0°C V _{CC} = +5 C _L = R _L =		
			Min	Тур	Max	Min	Max	
f _{MAX}	Maximum clock frequency	1	150	170		125		MHz
t _{PLH} t _{PHL}	Propagation delay CP to Qn	1	3.5 5.0	5.0 7.0	8.0 9.5	3.0 4.5	9.0 10.0	ns
t _{PHL}	Propagation delay MR to Qn	2	5.0	7.0	9.0	5.0	9.5	ns

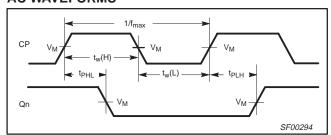
Octal D flip-flop

74F273A

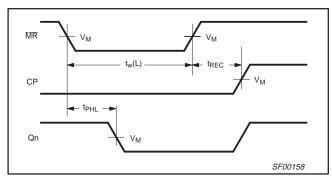
AC SETUP REQUIREMENTS FOR 'F273A

SYMBOL	PARAMETER	WAVEFORM	V	_{amb} = +25° ′ _{CC} = +5.0° C _L = 50pF R _L = 500Ω	V	T _{amb} = 0°C V _{CC} = +5 C _L = R _L =	50pF	UNIT
			Min	Тур	Max	Min	Max	
t _s (H) t _s (L)	Setup time, High or Low Dn to CP	3	3.0 2.0			2.5 2.5		
t _h (H) t _h (L)	Hold time, High or Low Dn to CP	3	0.5 0.0			2.5 1.0		ns
t _w (H) t _w (L)	Clock pulse width High or Low	1	4.5 3.5			5.0 4.0		ns
t _w (L)	Master Reset pulse width, Low	2	3.0			3.5		ns
t _{REC}	Recovery time MR to CP	2	4.0			5.0		ns

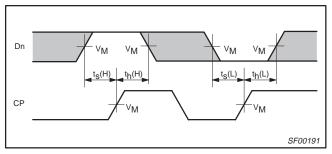
AC WAVEFORMS



Waveform 1. Propagation Delay, Clock Input to Output, Clock Pulse Width, and Maximum Clock Frequency



Waveform 2. Master Reset Pulse Width, Master Reset to Output **Delay and Master Reset to Clock Recovery Time**



Waveform 3. Data Setup and Hold Times

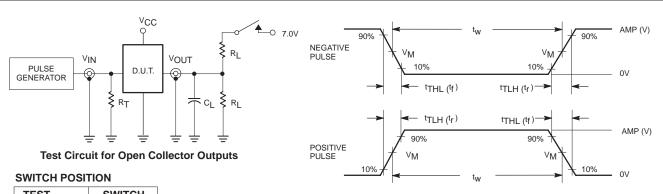
 $\mbox{NOTE:}$ For all waveforms, $\mbox{V}_{\mbox{\scriptsize M}}$ = 1.5V. The shaded areas indicate when the input is permitted to change for predictable output performance.

Product specification Philips Semiconductors

Octal D flip-flop

74F273A

TEST CIRCUIT AND WAVEFORMS



TEST	SWITCH
t _{PLZ}	closed
t _{PZL}	closed
All other	open

DEFINITIONS:

R_L = Load resistor;

see AC electrical characteristics for value.

Load capacitance includes jig and probe capacitance;
see AC electrical characteristics for value.

Termination resistance should be equal to Z_{OUT} of pulse generators. $R_T =$

family	INP	REMEN	TS			
lallilly	amplitude	V_{M}	rep. rate	t _w	t _{TLH}	t _{THL}
74F	3.0V	1.5V	1MHz	500ns	2.5ns	2.5ns

Input Pulse Definition

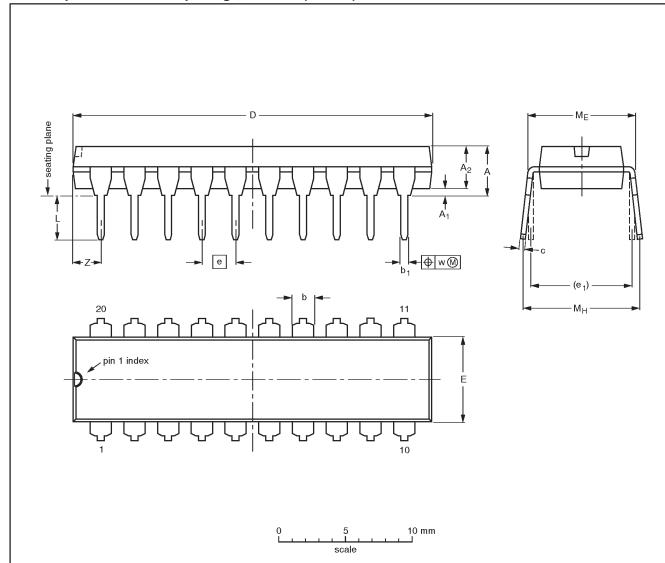
SF00128

Octal D flip-flop

74F273A

DIP20: plastic dual in-line package; 20 leads (300 mil)

SOT146-1



DIMENSIONS (inch dimensions are derived from the original mm dimensions)

UNIT	A max.	A ₁ min.	A ₂ max.	b	b ₁	С	D ⁽¹⁾	E ⁽¹⁾	е	e ₁	L	ME	Мн	w	Z ⁽¹⁾ max.
mm	4.2	0.51	3.2	1.73 1.30	0.53 0.38	0.36 0.23	26.92 26.54	6.40 6.22	2.54	7.62	3.60 3.05	8.25 7.80	10.0 8.3	0.254	2.0
inches	0.17	0.020	0.13	0.068 0.051	0.021 0.015	0.014 0.009	1.060 1.045	0.25 0.24	0.10	0.30	0.14 0.12	0.32 0.31	0.39 0.33	0.01	0.078

Note

1. Plastic or metal protrusions of 0.25 mm maximum per side are not included.

OUTLINE		REFER	RENCES	EUROPEAN	ISSUE DATE
VERSION	IEC	JEDEC	EIAJ	PROJECTION	ISSUE DATE
SOT146-1			SC603		92-11-17 95-05-24

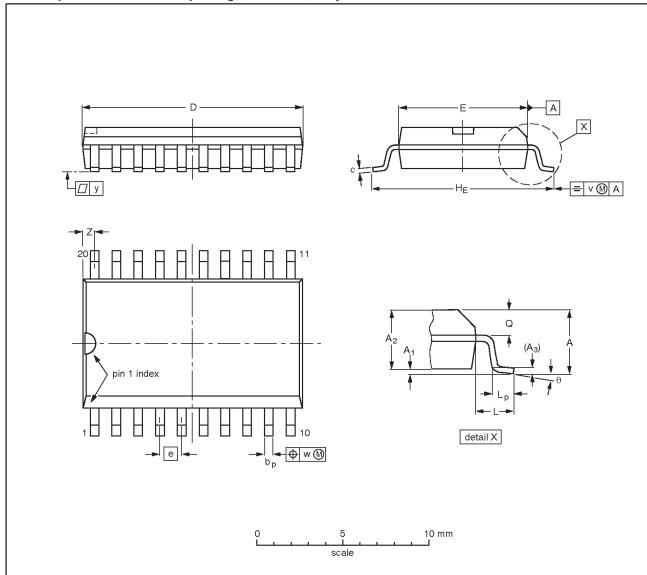
1996 Mar 12 8

Octal D flip-flop

74F273A

SO20: plastic small outline package; 20 leads; body width 7.5 mm

SOT163-1



DIMENSIONS (inch dimensions are derived from the original mm dimensions)

UNIT	A max.	A ₁	A ₂	A ₃	Ьp	С	D ⁽¹⁾	E ⁽¹⁾	е	HE	L	Lp	Q	v	w	у	z ⁽¹⁾	θ
mm	2.65	0.30 0.10	2.45 2.25	0.25	0.49 0.36	0.32 0.23	13.0 12.6	7.6 7.4	1.27	10.65 10.00	1.4	1.1 0.4	1.1 1.0	0.25	0.25	0.1	0.9 0.4	8°
inches	0.10	0.012 0.004	0.096 0.089	0.01	0.019 0.014	0.013 0.009	0.51 0.49	0.30 0.29	0.050	0.419 0.394	0.055	0.043 0.016	0.043 0.039	0.01	0.01	0.004	0.035 0.016	0°

Note

1. Plastic or metal protrusions of 0.15 mm maximum per side are not included.

OUTLINE		REFER	ENCES	EUROPEAN	ISSUE DATE	
VERSION	IEC	JEDEC	EIAJ	PROJECTION	ISSUE DATE	
SOT163-1	075E04	MS-013AC			-95-01-24 97-05-22	

Octal D flip-flop 74F273A

Data sheet status

Data sheet status	Product status	Definition [1]
Objective specification	Development	This data sheet contains the design target or goal specifications for product development. Specification may change in any manner without notice.
Preliminary specification	Qualification	This data sheet contains preliminary data, and supplementary data will be published at a later date. Philips Semiconductors reserves the right to make chages at any time without notice in order to improve design and supply the best possible product.
Product specification	Production	This data sheet contains final specifications. Philips Semiconductors reserves the right to make changes at any time without notice in order to improve design and supply the best possible product.

^[1] Please consult the most recently issued datasheet before initiating or completing a design.

Definitions

Short-form specification — The data in a short-form specification is extracted from a full data sheet with the same type number and title. For detailed information see the relevant data sheet or data handbook.

Limiting values definition — Limiting values given are in accordance with the Absolute Maximum Rating System (IEC 134). Stress above one or more of the limiting values may cause permanent damage to the device. These are stress ratings only and operation of the device at these or at any other conditions above those given in the Characteristics sections of the specification is not implied. Exposure to limiting values for extended periods may affect device reliability.

Application information — Applications that are described herein for any of these products are for illustrative purposes only. Philips Semiconductors make no representation or warranty that such applications will be suitable for the specified use without further testing or modification.

Disclaimers

Life support — These products are not designed for use in life support appliances, devices or systems where malfunction of these products can reasonably be expected to result in personal injury. Philips Semiconductors customers using or selling these products for use in such applications do so at their own risk and agree to fully indemnify Philips Semiconductors for any damages resulting from such application.

Right to make changes — Philips Semiconductors reserves the right to make changes, without notice, in the products, including circuits, standard cells, and/or software, described or contained herein in order to improve design and/or performance. Philips Semiconductors assumes no responsibility or liability for the use of any of these products, conveys no license or title under any patent, copyright, or mask work right to these products, and makes no representations or warranties that these products are free from patent, copyright, or mask work right infringement, unless otherwise specified.

Philips Semiconductors 811 East Arques Avenue P.O. Box 3409 Sunnyvale, California 94088–3409 Telephone 800-234-7381 © Copyright Philips Electronics North America Corporation 1998 All rights reserved. Printed in U.S.A.

print code Date of release: 10-98

Document order number: 9397-750-05113

Let's make things better.

Philips Semiconductors



